Product End-of-Life Disassembly Instructions

Product Category: Notebooks
Marketing Name / Model [List multiple models if applicable.]
HP 15 Laptop PC; HP Laptop; HP 15s Laptop PC; HP Laptop15X*; HP 250 15.6 inch G9 Notebook PC; HP 250 15.6" G9 Notebook PC; HP 250 G9; HP 256 15.6 inch G9 Notebook PC; HP 256 15.6" G9 Notebook PC; HP 256 G9

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP Inc. products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking or identification of location of parts or components requiring selective treatment, please contact HP's Sustainability Contact.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment. An "X" in the list of components and parts indicates the product contains the component or part requiring selective treatment

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) with a surface greater than 10 sq cm	☒ Main board (MB) PCB ☒ Solid state drive (SSD) PCB ☐ Wireless WAN module (WWAN) PCB ☐ Touch module PCB ☒ Power supply PCB ☐ External Keyboard (KB) ☐ External Mouse ☒ Others: DDR module	4
Batteries, excluding Li-Ion batteries. This includes standard alkaline, coin or button style batteries	☐ RTC/CMOS battery ☐ Others: _______________	0
Li-Ion batteries. Includes all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, etc.)	Li-ion battery(ies) are attached to the product by: ☒ screws ☐ snaps ☐ adhesive ☐ other. Explain ______	1
Mercury-containing components. For example, mercury in lamps, display backlights, scanner lamps, switches, batteries		0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm. Includes background illuminated displays with gas discharge lamps	☒ Panel LCD	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	☐ Power Supply capacitor(s) or condenser(s)	0
External electrical cables and cords	☒ AC power cord ☐ Audio, video or data cables ☐ Other: __________	1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants (not including external electrical cables and cords, PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner. Include the cartridges, print heads, tubes, vent chambers, and service stations.		0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0
Components containing chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons (HFC), hydrocarbons (HC)		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screwdriver	**Philip #0**

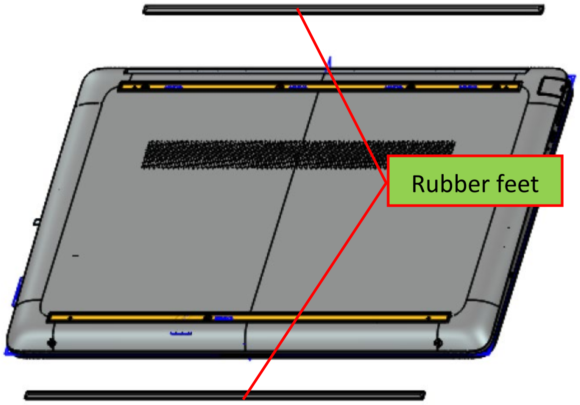
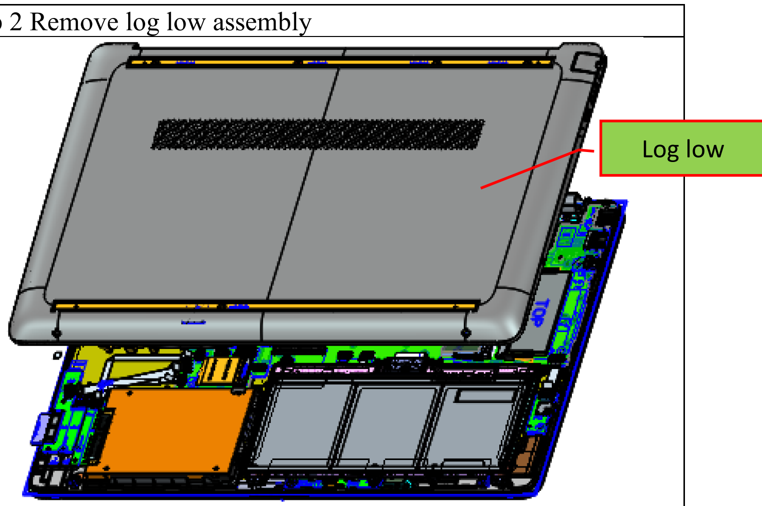
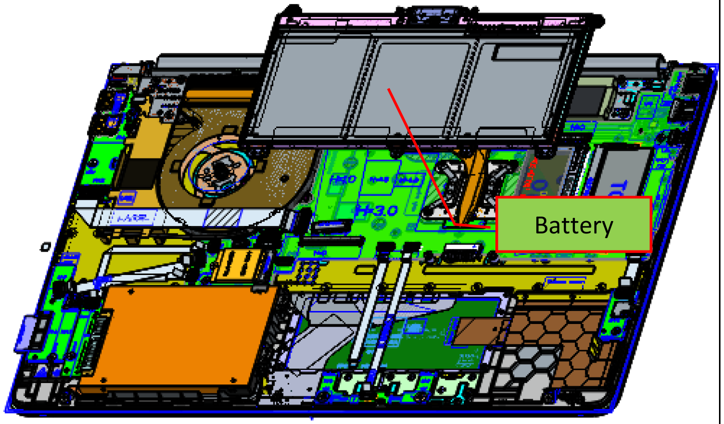
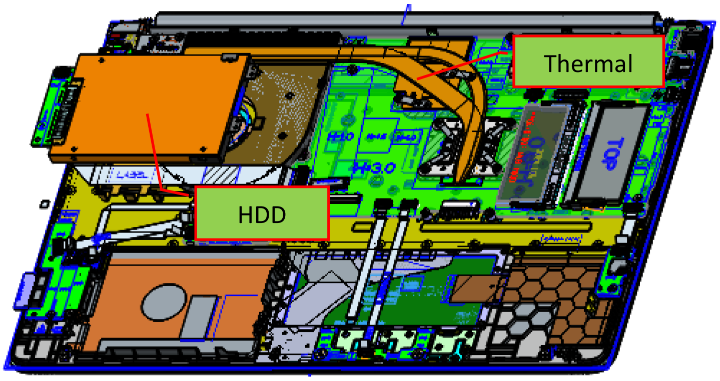
3.0 Product Disassembly Process

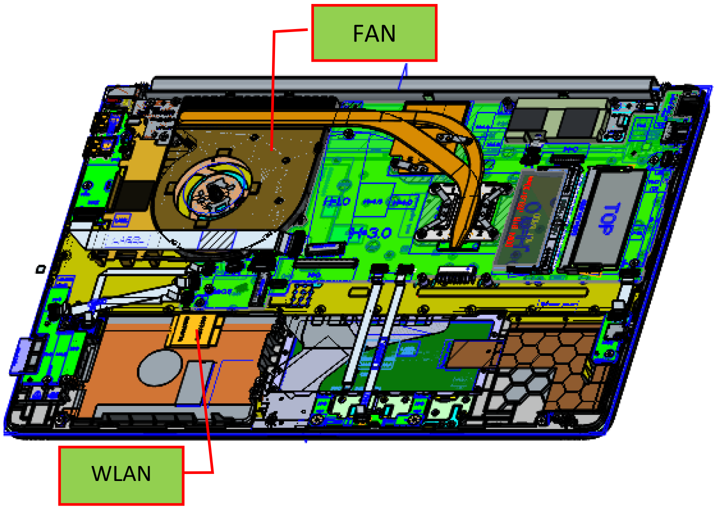
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure.

1. Remove rubber feet
2. Remove log low assembly
3. Remove Battery pack
4. Remove HDD assembly
5. Remove NGFF(WLAN)
6. Remove Hinge up assembly
7. Remove Mainboard and thermal module/PCB
8. Remove SD Board & USB Board & TP Board & Audio Board assembly
9. Remove Speaker & DC IN cable
10. Remove bezel & hinge cap assembly

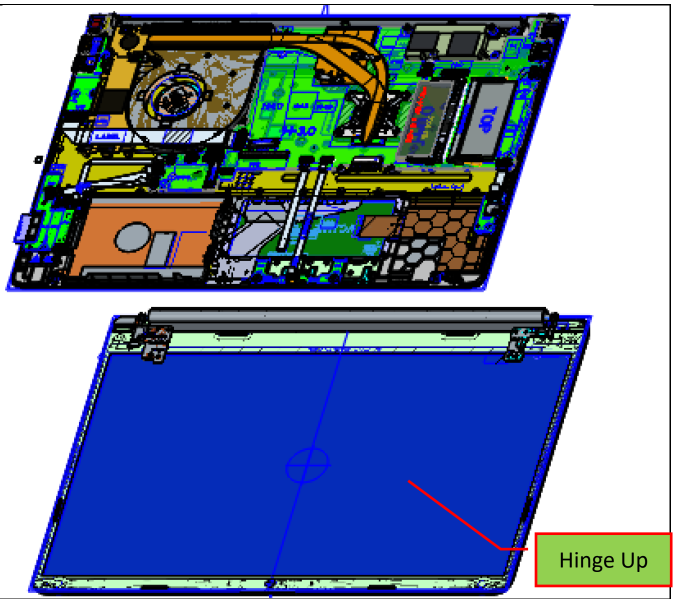
11. Remove LCD panel
12. Remove hinge R & hinge L assembly
13. Remove EDP cable & antenna cable

3.2 Location of components requiring selective treatment. The photos and/or graphics below identify the location of the parts or components requiring selective treatment within the main unit. For End-of-Life product disassembly instructions of external accessories including external power supply (EPS), external keyboard (KB) external mouse and external cables and cords, refer to the following URL: [End-of-Life Product Disassembly Instructions (hp.com)]

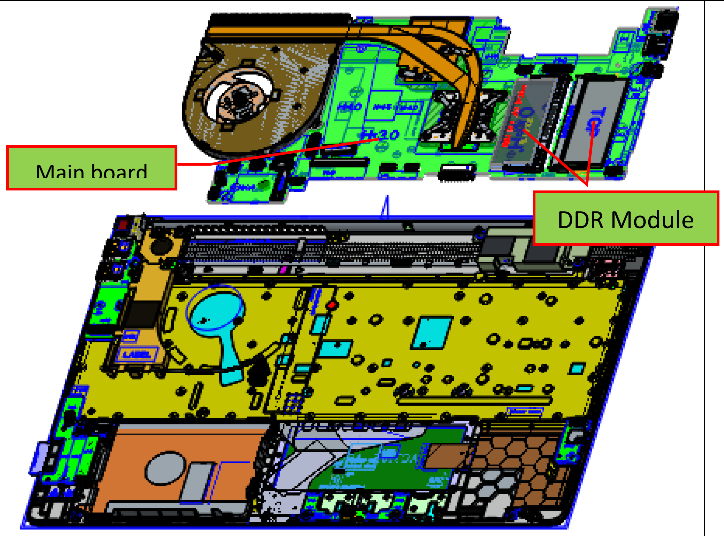
Step 1 Remove Rubber feet	Step 2 Remove log low assembly
	
Step 3 Remove Battery Pack	Step 4 Remove HDD assembly
	
Step 5 Remove NGFF(WLAN)	Step 6 Remove Hinge up assembly



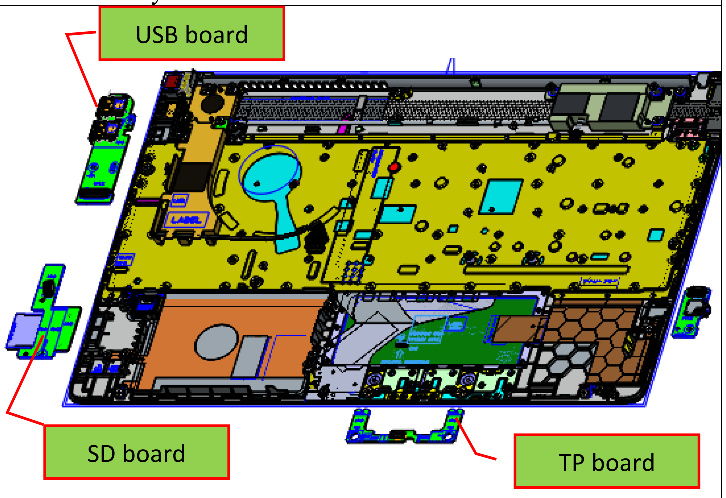
Step 7 Remove Mainboard and Thermal module/PCB



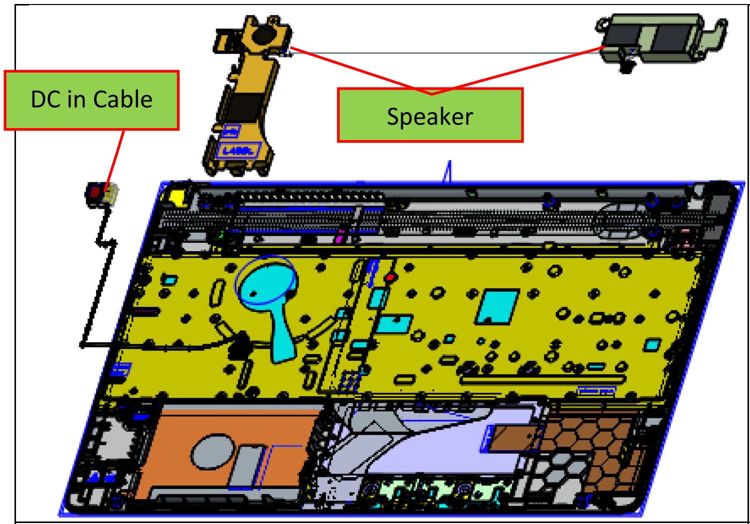
Step 8 Remove SD Board & USB Board & TP Board & Audio Board assembly

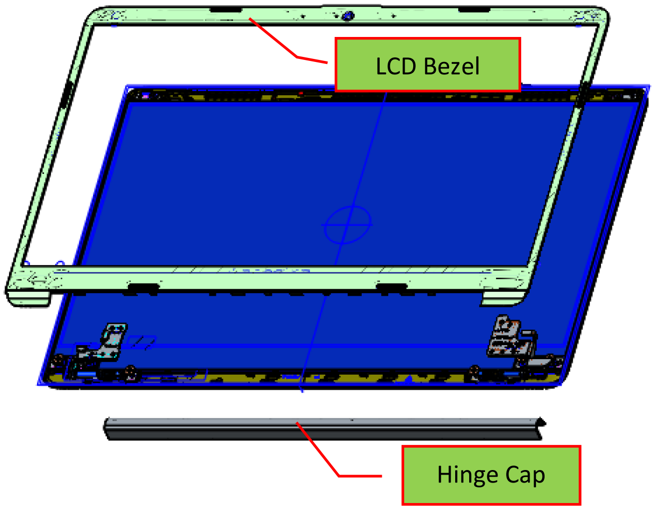


Step 9 Remove Speaker & DC IN cable

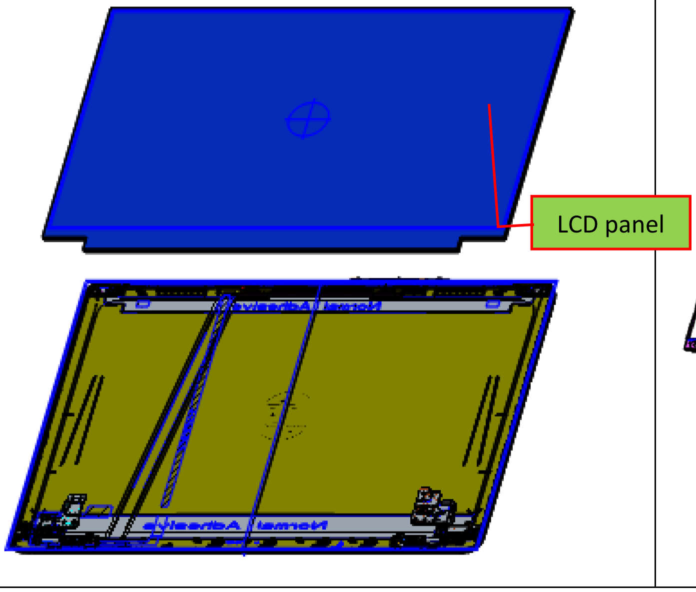


Step 10 Remove Bezel & hinge cap assembly

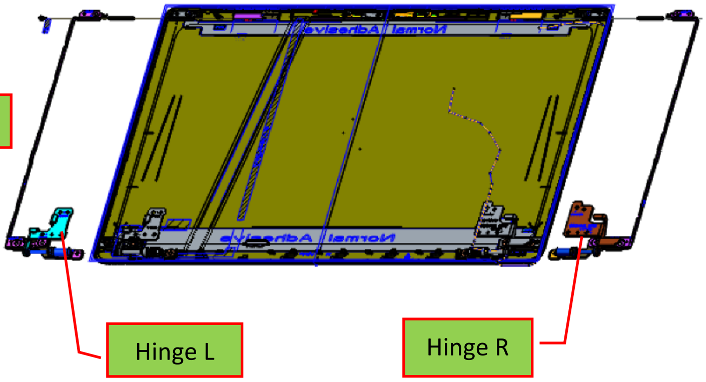




Step 11 Remove LCD panel



Step 12 Remove Hinge R & Hinge L assembly



Step 13 Remove EDP Cable & Antenna cable